

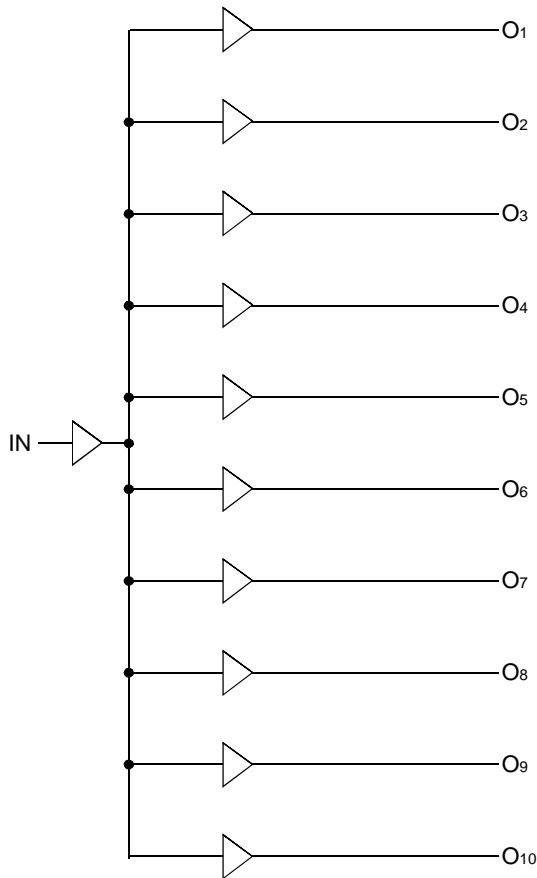
FEATURES:

- High frequency > 150MHz
- Guaranteed low skew < 150ps (max.) between any two outputs
- Very low duty cycle distortion < 300ps
- High speed: propagation delay < 3ns
- Very low CMOS power levels
- TTL compatible inputs and outputs
- 1:10 fanout
- Maximum output rise and fall time < 1.25ns (max.)
- Low input capacitance: 3pF typical
- 2.5V supply voltage
- Available in SSOP and QSOP packages

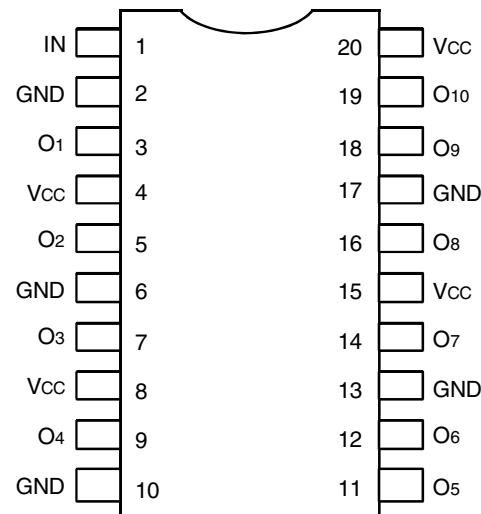
DESCRIPTION:

The FCT20807 is a 2.5V compatible, high speed, low noise, 1:10 fanout, non-inverting clock buffer. The large fanout from a single input reduces loading on the preceding driver and provides an efficient clock distribution network. Providing output to output skew as low as 150ps, the FCT20807 is an ideal clock distribution device for synchronous systems. Multiple power and grounds reduce noise. Typical applications are clock and signal distribution.

FUNCTIONAL BLOCK DIAGRAM



PIN CONFIGURATION

SSOP/ QSOP
TOP VIEW

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Symbol	Description	Max	Unit
VTERM ⁽²⁾	Terminal Voltage with Respect to GND	-0.5 to +4.6	V
VTERM ⁽³⁾	Terminal Voltage with Respect to GND	-0.5 to +5.5	V
VTERM ⁽⁴⁾	Terminal Voltage with Respect to GND	-0.5 to Vcc+0.5	V
TSTG	Storage Temperature	-65 to +150	°C
IOUT	DC Output Current	-60 to +60	mA

NOTES:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.
2. Vcc terminals.
3. Input terminals.
4. Outputs and I/O terminals.

CAPACITANCE ($T_A = +25^\circ\text{C}$, $f = 1.0\text{MHz}$)

Symbol	Parameter ⁽¹⁾	Conditions	Typ.	Max.	Unit
CIN	Input Capacitance	$V_{IN} = 0\text{V}$	3	4	pF
COUT	Output Capacitance	$V_{OUT} = 0\text{V}$	—	6	pF

NOTE:

1. This parameter is measured at characterization but not tested.

PIN DESCRIPTION

Pin Names	Description
IN	Clock Inputs
Ox	Clock Outputs

POWER SUPPLY CHARACTERISTICS

Symbol	Parameter	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Unit
ICCL	Quiescent Power Supply Current	Vcc = Max.		—	0.1	20	μA
ICCH	TTL Inputs HIGH	$V_{IN} = \text{GND}$ or V_{cc}					
ΔICC	Power Supply Current per Input HIGH	Vcc = Max.		—	45	300	μA
ICCD	Dynamic Power Supply Current per Output ⁽³⁾	Vcc = 2.7V 15 pF	150 MHz	—	40	—	μA /MHz
IC	Total Power Supply Current ⁽⁴⁾	Vcc = Max.	$V_{IN} = V_{cc}$	—	65	90	mA
		$D_H = 12\text{pF}$	$V_{IN} = \text{GND}$	—	75	100	
		All outputs toggling $f_i = 150\text{MHz}$	$V_{IN} = V_{cc} - 0.6\text{V}$ $V_{IN} = \text{GND}$	—			

NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.

2. Typical values are at $V_{cc} = 2.5\text{V}$, $+25^\circ\text{C}$ ambient.

3. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.

4. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$

$$I_C = I_{CC} + \Delta I_{CC} D_H N_T + I_{CCD} (f_i)$$

I_{CC} = Quiescent Current (ICCL, ICCH and ICCT)

ΔI_{CC} = Power Supply Current for a TTL High Input ($V_{IN} = V_{cc} - 0.6\text{V}$)

D_H = Duty Cycle for TTL Inputs High

N_T = Number of TTL Inputs at D_H

I_{CCD} = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)

f_i = Input Frequency

DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified

Industrial: $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$, $V_{CC} = 2.5\text{V} \pm 0.2\text{V}$

Symbol	Parameter	Test Conditions ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Unit
V_{IH}	Input HIGH Level		1.7	—	—	V
V_{IL}	Input LOW Level		—	—	0.7	V
I_{IH}	Input HIGH Current (Input pins)	$V_{CC} = \text{Max.}$, $V_I = V_{CC}$	—	—	± 1	mA
I_{IL}	Input LOW Current (Input pins)	$V_{CC} = \text{Max.}$, $V_I = \text{GND}$	—	—	± 1	mA
V_{IK}	Clamp Diode Voltage	$V_{CC} = \text{Min.}$, $I_{IN} = -18\text{mA}$	—	-0.7	-1	V
I_{ODH}	Output HIGH Current	$V_{CC} = 2.5\text{V}$, $V_{IN} = V_{IH}$ or V_{IL} , $V_O = 1.25\text{V}^{(3)}$	-25	-45	-100	mA
I_{ODL}	Output LOW Current	$V_{CC} = 2.5\text{V}$, $V_{IN} = V_{IH}$ or V_{IL} , $V_O = 1.25\text{V}^{(3)}$	20	55	120	mA
V_{OH}	Output HIGH Voltage	$V_{CC} = \text{Min.}$	$I_{OH} = -1\text{mA}$	$V_{CC} - 0.2$	—	V
		$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -8\text{mA}$	1.8 ⁽⁵⁾	—	
V_{OL}	Output LOW Voltage	$V_{CC} = \text{Min.}$	$I_{OL} = 1\text{mA}$	—	0.4	V
		$V_{IN} = V_{IH}$ or V_{IL}	$I_{OL} = 8\text{mA}$	—	0.6	
I_{OS}	Short Circuit Current ⁽⁴⁾	$V_{CC} = \text{Max.}$, $V_O = \text{GND}^{(3)}$	-25	-60	-135	mA

NOTES:

1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at $V_{CC} = 2.5\text{V}$, $+25^\circ\text{C}$ ambient.
3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
4. This parameter is guaranteed but not tested.
5. $V_{OH} = V_{CC} - 0.6\text{V}$ at rated current.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE^(1,2)

Following Conditions Apply Unless Otherwise Specified

Industrial: TA = -40°C to +85°C, V_{CC} = 2.5V ± 0.2V

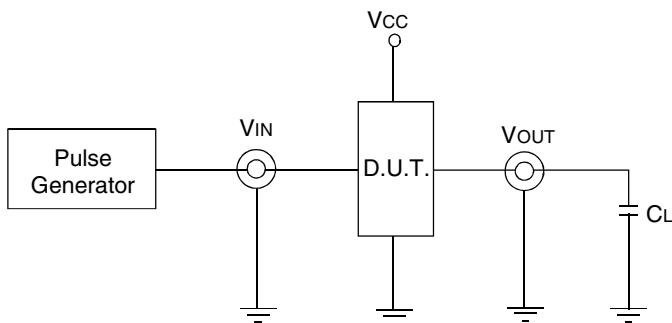
Symbol	Parameter	Conditions ⁽³⁾	Min.	Typ.	Max.	Unit
t _{PLH}	Propagation Delay	CL = 22pF 100 MHz	—	3	3.5	ns
t _{PHL}			—	1	1.25	ns
t _R	Output Rise Time		—	1	1.25	ns
t _F	Output Fall Time		—	100	150	ps
t _{SK(O)}	Same Device Output Pin-to-Pin Skew ⁽⁴⁾		—	250	300	ps
t _{SK(P)}	Pulse Skew ⁽⁵⁾		—	400	600	ps
t _{SK(PP)}	Part-to-Part Skew ⁽⁶⁾					

Symbol	Parameter	Conditions ^(3,7)	Min.	Typ.	Max.	Unit
t _{PLH}	Propagation Delay	CL = 12pF 150 MHz	—	2.4	2.7	ns
t _{PHL}			—	1	1.2	ns
t _R	Output Rise Time		—	1	1.2	ns
t _F	Output Fall Time		—	100	150	ps
t _{SK(O)}	Same Device Output Pin-to-Pin Skew ⁽⁴⁾		—	250	300	ps
t _{SK(P)}	Pulse Skew ⁽⁵⁾		—	400	600	ps
t _{SK(PP)}	Part-to-Part Skew ⁽⁶⁾					

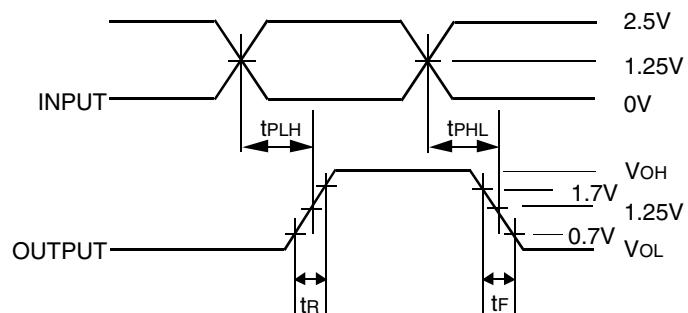
NOTES:

1. t_{PLH} and t_{PHL} are production tested. All other parameters guaranteed but not production tested.
2. Propagation delay range indicated by Min. and Max. limit is due to V_{CC}, operating temperature and process parameters. These propagation delay limits do not imply skew.
3. See test circuits and waveforms.
4. Skew measured between all outputs under identical transitions and load conditions.
5. Skew measured is difference between propagation delay times t_{PHL} and t_{PLH} of same output under identical load conditions.
6. Part to part skew for all outputs given identical transitions and load conditions at identical V_{CC} levels and temperature.
7. Airflow of 1m/s is recommended for frequencies above 133MHz.

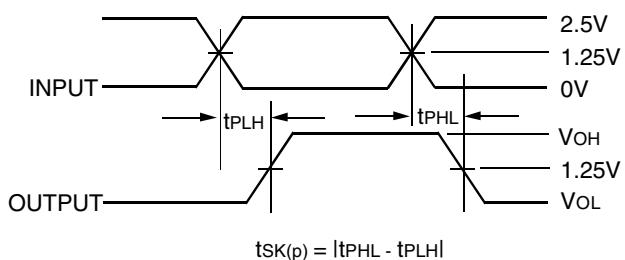
TEST CIRCUITS AND WAVEFORMS



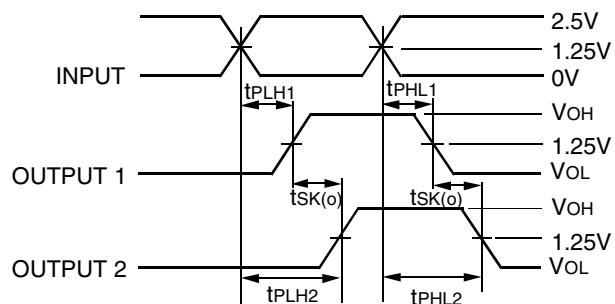
C_L = Load Capacitance: Includes Jig and Probe Capacitance



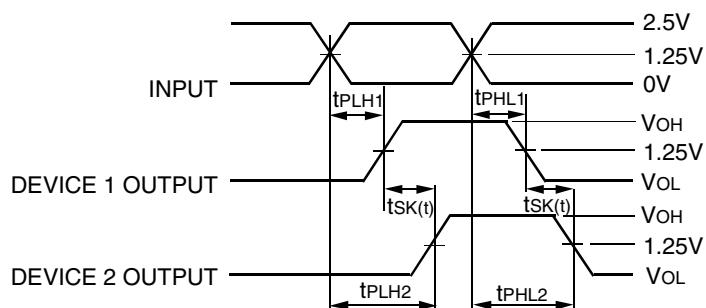
Propagation Delay



Pulse Skew - $t_{SK}(P)$



Output Skew - $t_{SK}(O)$



Part-to-Part Skew - $t_{SK}(PP)$

NOTE: Device 1 and device 2 are same package type and speed grade.

TEST CONDITIONS

Symbol	$V_{CC} = 2.5V \pm 0.2V$	Unit
C_L	$22^{(1)}$	pF
	$12^{(2)}$	
R_T	Z_{out} of pulse generator	Ω
t_R / t_F	$1.25^{(1)}$	ns
	$1.2^{(2)}$	

DEFINITIONS:

C_L = Load capacitance: includes jig and probe capacitance.

R_T = Termination resistance: should be equal to Z_{out} of the Pulse Generator.

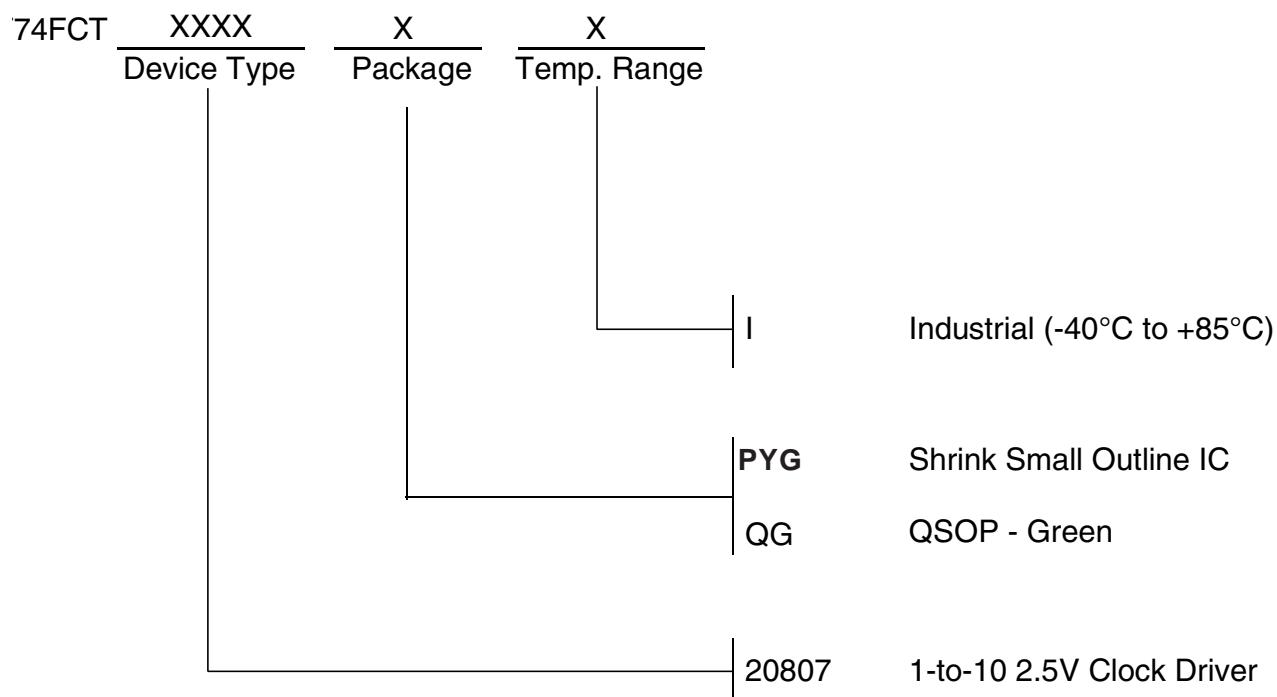
t_R / t_F = Rise/Fall time of the input stimulus from the Pulse Generator.

NOTES:

1. Test conditions at 100MHz.

2. Test conditions at 150MHz.

ORDERING INFORMATION



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